



HALF-BRIDGE GATE DRIVER IN SO-8

Description

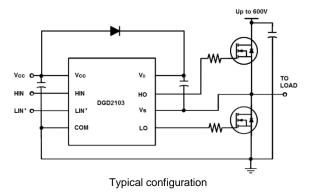
The DGD2103 is a high-voltage / high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half-bridge configuration. High voltage processing techniques enable the DGD2103's high side to switch to 600V in a bootstrap operation.

The DGD2103 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver output features high pulse current buffers designed for minimum driver cross conduction. DGD2103 has a fixed internal deadtime of 520ns (typical).

The DGD2103 is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Applications

- **DC-DC** Converters •
- **DC-AC Inverters**
- **AC-DC Power Supplies**
- Motor Controls
- **Class D Power Amplifiers**



Ordering Information (Note 4)

Fea	atur	es					

- Floating high-side driver in bootstrap operation to 600V . Drives two N-channel MOSFETs or IGBTs in a half-bridge
- configuration 290mA source/600mA sink output current capability
- Outputs tolerant to negative transients
- Internal dead time of 520ns to protect MOSFETs
- Wide low side gate driver supply voltage: 10V to 20V
- Logic input (HIN and LIN*) 3.3V capability
- Schmitt triggered logic inputs
- Undervoltage lockout for V_{CC} (logic and low side supply)
- Extended temperature range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-8 (Type TH)
- Case material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.075 grams (Approximate)



SO-8 (Type TH) Top View

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DGD2103S8-13	DGD2103	13	12	2,500

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes: 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

- and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

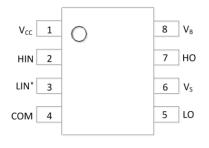


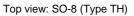
= Manufacturer's marking ווכ DGD2103 = Product Type Marking Code YΥ = Year (ex: 16 = 2016) WW

= Week (01 - 53)



Pin Diagrams

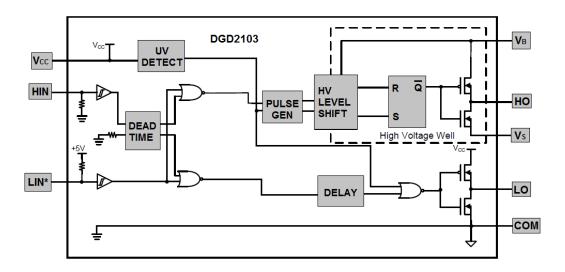




Pin Descriptions

Pin Number	Pin Name	Function	
1	V _{CC}	Logic and Low Side Supply	
2	HIN	Logic Input for High-Side Gate Driver Output in Phase with HO	
3	LIN*	Logic input for Low-Side Gate Driver Output out of Phase with LO	
4	COM	Low-Side and Logic Return	
5	LO	Low-Side Gate Drive Output	
6	Vs	High-Side Floating Supply Return	
7	HO	High-Side Gate Drive Output	
8	VB	High-Side Floating Supply	

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	VB	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dV _S / dt	50	V/ns
Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN*)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	PD	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	200	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (soldering, 10s)	TL	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Мах	Unit
High Side Floating Supply Absolute Voltage	V _B	V _s + 10	V _s + 20	V
High Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High Side Floating Output Voltage	V _{HO}	Vs	V _B	V
Low Side Supply Voltage	V _{cc}	10	20	V
Low Side Output Voltage	V _{LO}	0	V _{cc}	V
Logic Input Voltage (HIN & LIN*)	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to - V_{BS} .



DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" (HIN) & Logic "0" (LIN*) Input Voltage	VIH	2.5	-	_	V	V _{CC} = 10V to 20V
Logic "0" (HIN) & Logic "1" (LIN*) Input Voltage	VIL	-	-	0.8	V	$V_{CC} = 10V$ to 20V
High Level Output Voltage, V _{BIAS} - V _O	V _{OH}	-	0.05	0.2	V	$I_0 = 2mA$
Low Level Output Voltage, V _O	V _{OL}	-	0.02	0.1	V	$I_0 = 2mA$
Offset Supply Leakage Current	I _{LK}	-	-	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	-	60	100	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	lccq	-	350	500	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	-	3	10	μA	HIN = 5V, LIN* = 0V
Logic "0" Input Bias Current	I _{IN-}	-	-	5	μA	$HIN = 0V, LIN^* = 5V$
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	8.0	8.9	9.8	V	-
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV-}	7.4	8.2	9.0	V	—
Output High Short Circuit Pulsed Current	I _{O+}	130	290	-	mA	V _O = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I _{O-}	270	600	-	mA	V _O = 15V, PW ≤ 10µs

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins: HIN and LIN*. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	toN	-	680	820	ns	$V_{\rm S} = 0V$
Turn-off Propagation Delay	toFF	-	150	220	ns	V _S = 600V
Delay Matching, HO & LO turn-on/turn-off	t _{DM}	-	_	60	ns	-
Turn-on Rise Time	tr	-	70	170	ns	$V_{\rm S} = 0V$
Turn-off Fall Time	tf	-	35	90	ns	$V_{\rm S} = 0V$
Deadtime: t _{DT LO-HO} & t _{DT HO-LO}	t _{DT}	400	520	650	ns	-



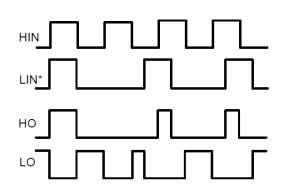


Figure 1. Input / Output Timing Diagram

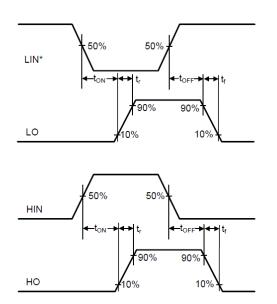


Figure 2. Switching Time Waveform Definitions

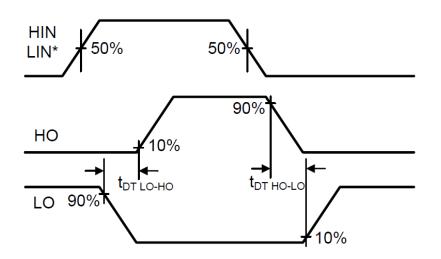
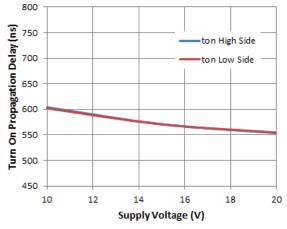


Figure 3. Deadtime Waveform Definitions





Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

Figure 4. Turn-on Propagation Delay vs. Supply Voltage

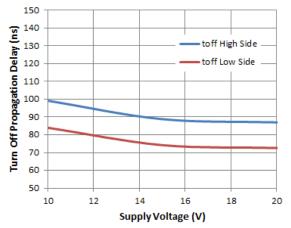
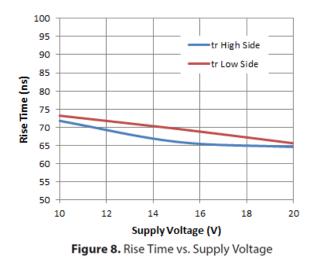


Figure 6. Turn-off Propagation Delay vs. Supply Voltage



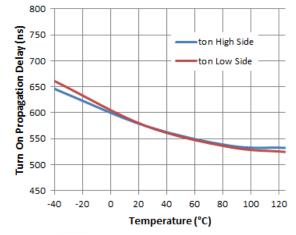


Figure 5. Turn-on Propagation Delay vs. Temperature

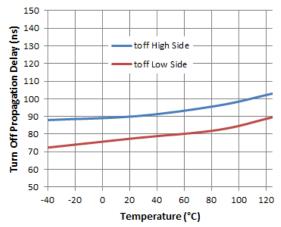
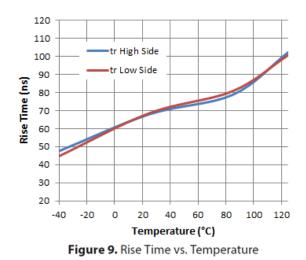


Figure 7. Turn-off Propagation Delay vs. Temperature



DGD2103 Document Number DS38278 Rev. 3 - 2



tf High Side

tf Low Side

0

0

0

20

40

Temperature (°C)

60

80

100 120

20

40

Temperature (°C)

60

20

40

Temperature (°C)

60

80

IBSq

ICCq

80

tdmon

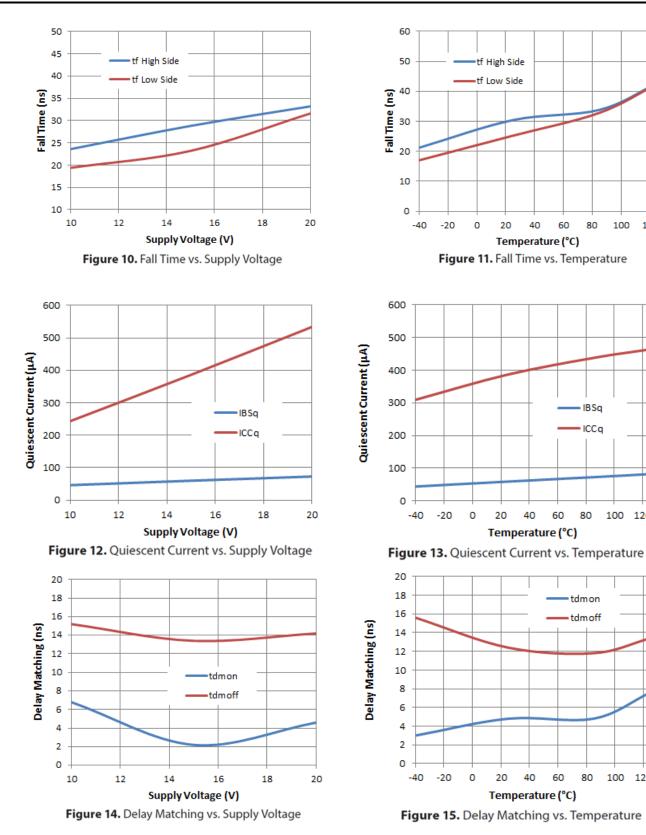
tdmoff

100 120

100

120

Typical Performance Characteristics (continued)





Typical Performance Characteristics (cont.)

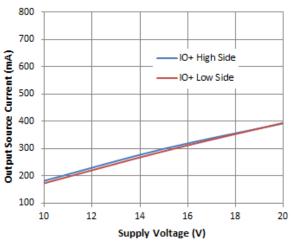


Figure 16. Output Source Current vs. Supply Voltage

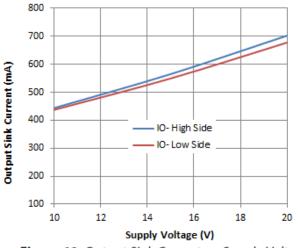


Figure 18. Output Sink Current vs. Supply Voltage

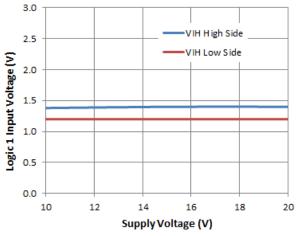


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

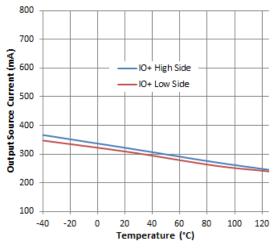
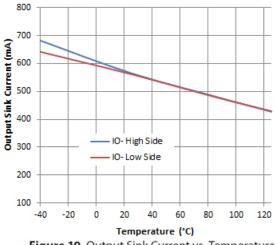


Figure 17. Output Source Current vs. Temperature





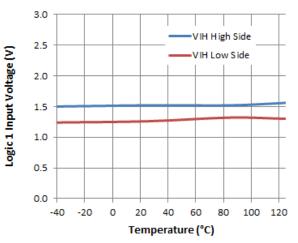


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (cont.)

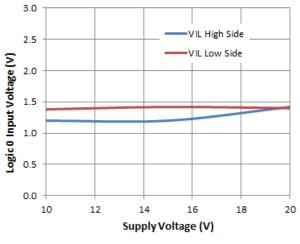


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

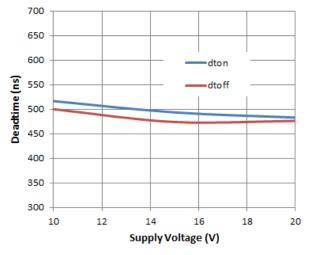


Figure 24. Deadtime vs. Supply Voltage

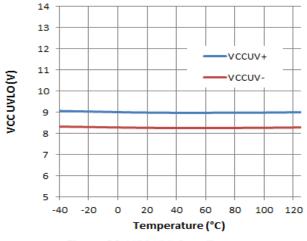


Figure 26. VCC UVLO vs. Temperature

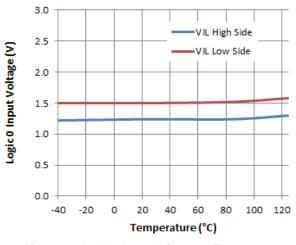


Figure 23. Logic 0 Input Voltage vs. Temperature

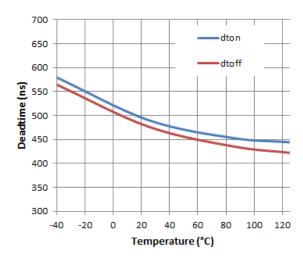


Figure 25. Deadtime vs. Temperature

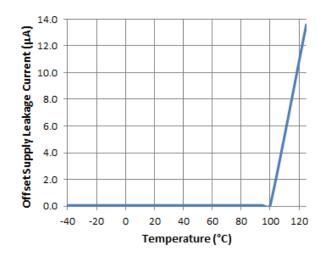
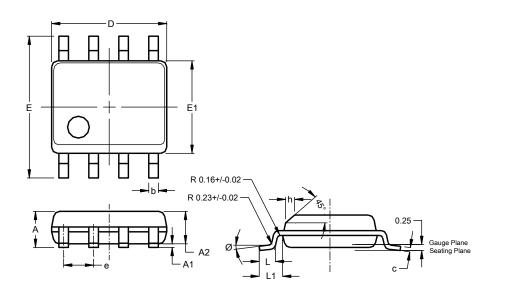


Figure 27. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

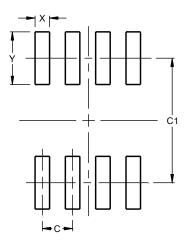
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



SO-8 (Type TH)						
Dim	Min	Max	Тур			
Α	1.35	1.75				
A1	0.10	0.25				
A2			1.45			
b	0.35	0.51				
C	0.190	0.248				
D	4.80	5.00	4.90			
Е	5.80	6.20	6.00			
E1	3.80	4.00	3.90			
е			1.27			
h	0.25	0.50				
L	0.41	1.27				
L1			1.04			
Ø	0°	8°				
All [Dimensi	ons in	mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Y	2.20

Note : For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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